



Description

The GM76C256CL/CLL-W is a 262,144 bits static random access memory organized as 32,768 words by 8 bits. Using a $0.8\mu\text{m}$ advanced CMOS technology and operated from a single 2.7V to 5.5V supply. Advanced circuit techniques provide both high speed and low power consumption. The GM76C256CL/CLL-W has Chip select /CS, which allows for device selection and data retention control, and output enable (/OE), which provides fast memory access. Thus it is suitable for high speed and low power applications, particularly where battery back-up is required. The GM76C256CL/CLL-W is offered in a 28-pin DIP, SOP and TSOP I.

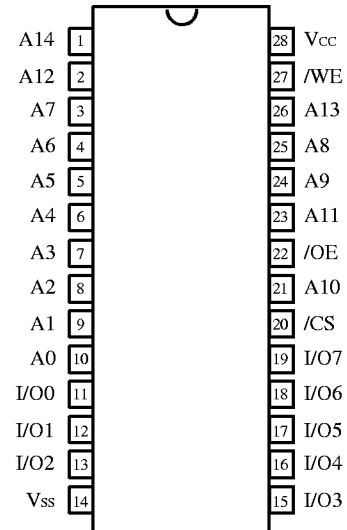
Features

- * Fast Speed : 55/70ns at $V_{cc}=5V\pm 10\%$
120/150ns at $V_{cc}=3V\pm 10\%$
- * Low Power Standby and Low Power Operation
Standby : 110uW (Max) at $V_{cc}=5V\pm 10\%$
33uW (Max) at $V_{cc}=3V\pm 10\%$
Operation : 385mW (Max) at $V_{cc}=5V\pm 10\%$
99mW (Max) at $V_{cc}=3V\pm 10\%$
- * Completely Static RAM : No Clock or Timing Strobe Required
- * Equal Access and Cycle Time
- * Capability of Battery Back-up Operation
- * Single + 2.7 ~ 5.5V Operation
- * Standard 28 DIP, SOP and TSOP I

Pin Description

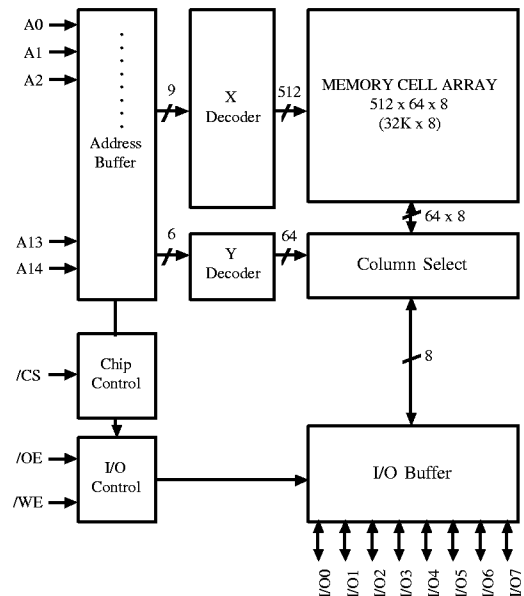
Pin	Function
A0-A14	Address Inputs
/WE	Write Enable Input
/OE	Output Enable Input
/CS	Chip Select Input
I/O0-I/O7	Data Input/Output
V _{cc}	Power Supply
V _{ss}	Ground

Pin Configuration



(Top View)

Block Diagram



Absolute Maximum Ratings ^{*1}

Symbol	Parameter	Rating	Unit
T _A	Ambient Temperature under Bias	0 ~ 70	C
T _{STG}	Storage Temperature	-65 ~ 150	C
V _{SOL}	Soldering Temperature and Time	260, 10 (at lead)	C, S
V _{CC}	Supply Voltage	-0.3 ~ 7.0	V
V _{IN}	Input Voltage	-0.3 ^{*2} ~ 7.0	V
V _{IO}	Input and Output Voltage	-0.5 ~ V _{CC} + 0.5	V
P _D	Power Dissipation	1.0	W

Notes:

1. Operation at above Absolute Maximum Ratings can adversely affect device reliability.
2. -3.0V at pulse width 50ns Max.

Recommended Operating Conditions (T_A = 0 ~ 70C)

Symbol	Parameter	V _{CC} = 5V +/- 10%			V _{CC} = 2.7 ~ 5.5V			Unit
		Min	Typ	Max	Min	Typ	Max	
V _{CC}	Supply Voltage	4.5	5.0	5.5	2.7	3.0	5.5	V
V _{IH}	Input High Voltage	2.2	-	V _{CC} + 0.3	2.2	-	V _{CC} + 0.3	V
V _{IL}	Input Low Voltage	-0.3*	-	0.8	-0.3*	-	0.4	V

*Note: V_{IL} = -0.3V Min for pulse width less than 50ns.

Truth Table

/CS	/WE	/OE	Input/Output	MODE
H	X	X	Hi-Z	Not Selected
L	H	L	Output Data	Read
L	L	X	Input Data	Write
L	H	H	Hi-Z	Output Disable

*Note: X means "don't care".

DC Electrical Characteristics ($V_{CC}=5V\pm10\%$, $3V\pm10\%$, $T_A = 0 \sim 70^\circ\text{C}$)

Symbol	Parameter	Conditions	$V_{CC} = 3V\pm10\%$			$V_{CC} = 5V\pm10\%$			Unit
			Min	Typ	Max	Min	Typ	Max	
$I_{I(L)}$	Input Leakage Current	$V_{IN} = 0 \text{ to } V_{CC}$	-1	-	1	-1	-	1	μA
$I_{O(L)}$	Output Leakage Current	$/CS = V_{IH} \text{ or } /OE = V_{IH} \text{ or } /WE = V_{IL}, V_{SS} \leq V_{OUT} \leq V_{CC}$	-1	-	1	-1	-	1	μA
V_{OH}	High Level Output Voltage	$I_{OH} = -1.0\text{mA}$	2.2	-	-	2.4	-	-	V
V_{OL}	Low Level Output Voltage	$I_{OL} = 2.1\text{mA}$	-	-	0.4	-	-	0.4	V
I_{CC}	Operating Supply Current	$/CS = V_{IL}, V_{IN} = V_{IH}/V_{IL}, I_{IO} = 0\text{mA}$	-	0.6	2	-	7	10	mA
I_{CC1}	Average Operating Current	$/CS = V_{IL}, V_{IN} = V_{IH}/V_{IL}, I_{IO} = 0\text{mA}$ tcycle = Min, cycle	-	-	30	-	-	70	mA
I_{CC2}	Average Operating Current	$/CS = V_{IL}, V_{IN} = V_{IH}/V_{IL}, I_{IO} = 0\text{mA}$ tcycle = 1 μs , cycle	-	-	5	-	-	10	mA
I_{CCS1}	Standby Current (TTL)	$/CS = V_{IH}$	-	-	0.3	-	-	1	mA
I_{CCS2}	Standby Current (CMOS)	$/CS \geq V_{CC}-0.2\text{V}$ L-W	-	-	20	-	-	40	μA
		LL-W	-	-	10	-	-	20	μA

*TYP. Values are measured at 25°C , $V_{CC} = 5\text{V}$

AC Operating Characteristics (3.0V $\pm$ 10% , T_A = 0 ~ 70C)

Read Cycle

Symbol	Parameter	Condi- tions	GM76C256C-55W		GM76C256C-70W		Unit
			Min	Max	Min	Max	
t _{RC}	Read Cycle Time	*1	120	-	150	-	ns
t _{AA}	Address Access Time		-	120	-	150	ns
t _{ACS}	Chip Select Access Time		-	120	-	150	ns
t _{OE}	Output Enable Access Time		-	55	-	60	ns
t _{OH}	Output Hold Time		10	-	10	-	ns
t _{CLZ}	Chip Selection to Output in Low-Z	*2	10	-	15	-	ns
t _{OLZ}	Output Disable to Output in Low-Z		10	-	15	-	ns
t _{CHZ}	Chip Deselection to Output in High-Z		0	40	0	50	ns
t _{OHZ}	Output Disable to Output in High-Z		0	40	0	50	ns

Write Cycle

Symbol	Parameter	Condi- tions	GM76C256C-55W		GM76C256C-70W		Unit
			Min	Max	Min	Max	
t _{WC}	Write Cycle Time	*1	120	-	150	-	ns
t _{CW}	Chip Select to End of Write		100	-	120	-	ns
t _{AW}	Address Set-up Time to End of Write		100	-	120	-	ns
t _{AS}	Address Set-up Time		0	-	0	-	ns
t _{WP}	Write Pulse Width		65	-	70	-	ns
t _{WR}	Write Recovery Time		0	-	0	-	ns
t _{DW}	Data to Write Time Overlap		40	-	50	-	ns
t _{DH}	Data Hold Time		0	-	0	-	ns
t _{WHZ}	Write to Output in High-Z	*2	0	40	0	50	ns
t _{OW}	Output Active from End of Write		10	-	15	-	ns

*1 Test Conditions.

1. Input pulse level : 0.4V to 2.2V
2. t_r = t_f = 5ns
3. Input/output timing reference level : 1.5V
4. Output load C_L = 100pF + 1TTL Load

*2 Test Conditions.

1. Input pulse level : 0.4V to 2.2V
2. t_r = t_f = 5ns
3. Input timing reference level : 1.5V
4. Output timing reference level :
+/-200mV (the level displacement from
stable output voltage level)
5. Output load C_L = 5pF + 1TTL Load

AC Operating Characteristics (5.0V $\pm$ 10% , T_A = 0 ~ 70C)

Read Cycle

Symbol	Parameter	Condi- tions	GM76C256C-55W		GM76C256C-70W		Unit
			Min	Max	Min	Max	
t _{RC}	Read Cycle Time	*1	55	-	70	-	ns
t _{AA}	Address Access Time		-	55	-	70	ns
t _{ACS}	Chip Select Access Time		-	55	-	70	ns
t _{OE}	Output Enable Access Time		-	25	-	30	ns
t _{OH}	Output Hold Time		10	-	10	-	ns
t _{CLZ}	Chip Selection to Output in Low-Z	*2	10	-	10	-	ns
t _{OLZ}	Output Disable to Output in Low-Z		5	-	5	-	ns
t _{CHZ}	Chip Deselection to Output in High-Z		0	20	0	25	ns
t _{OHZ}	Output Disable to Output in High-Z		0	20	0	25	ns

Write Cycle

Symbol	Parameter	Condi- tions	GM76C256C-55W		GM76C256C-70W		Unit
			Min	Max	Min	Max	
t _{WC}	Write Cycle Time	*1	55	-	70	-	ns
t _{CW}	Chip Select to End of Write		45	-	60	-	ns
t _{AW}	Address Set-up Time to End of Write		45	-	60	-	ns
t _{AS}	Address Set-up Time		0	-	0	-	ns
t _{WP}	Write Pulse Width		40	-	50	-	ns
t _{WR}	Write Recovery Time		0	-	0	-	ns
t _{DW}	Data to Write Time Overlap		25	-	30	-	ns
t _{DH}	Data Hold Time		0	-	0	-	ns
t _{WHZ}	Write to Output in High-Z	*2	0	20	0	25	ns
t _{OW}	Output Active from End of Write		5	-	5	-	ns

*1 Test Conditions.

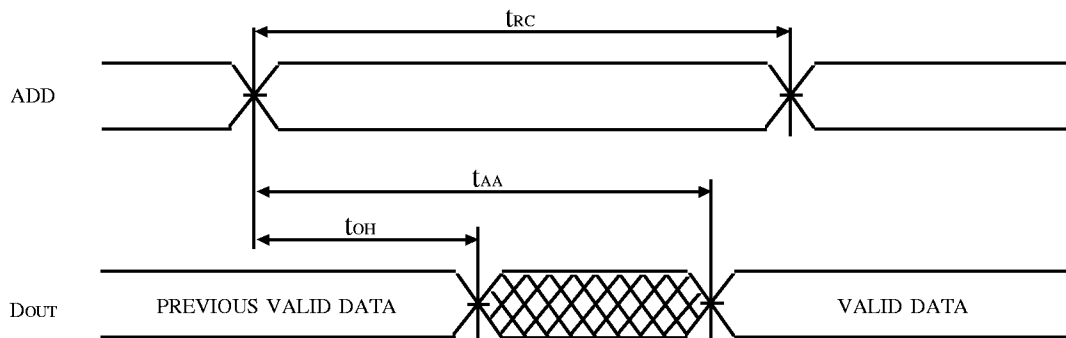
1. Input pulse level : 0.6V to 2.4V
2. t_r = t_f = 5ns
3. Input/output timing reference level : 1.5V
4. Output load C_L = 100pF + 1TTL Load

*2 Test Conditions.

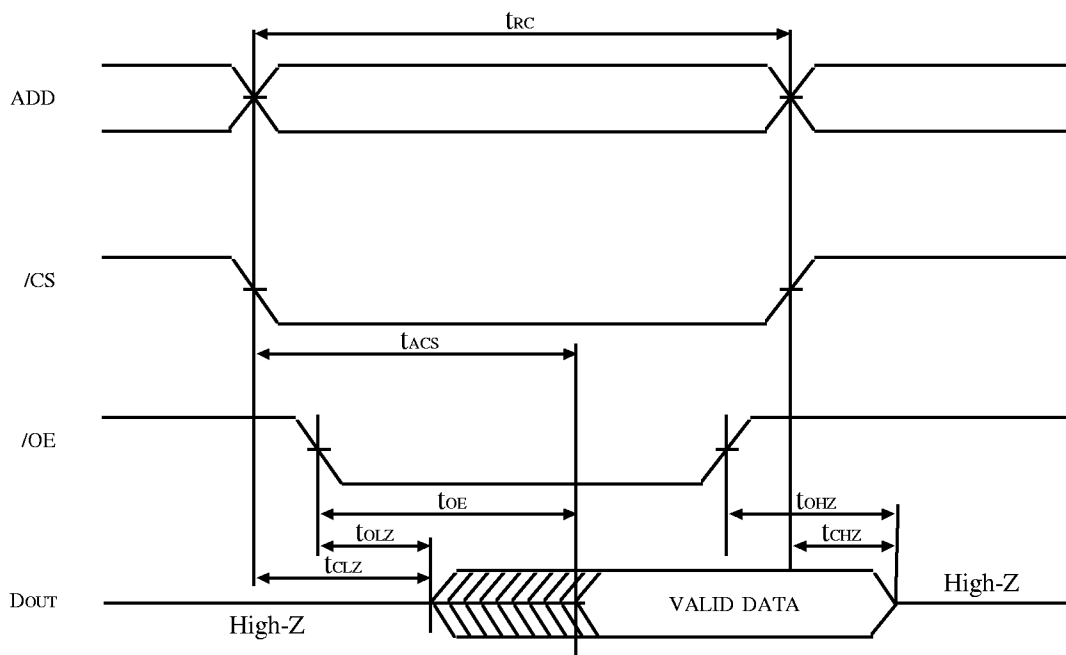
1. Input pulse level : 0.6V to 2.4V
2. t_r = t_f = 5ns
3. Input timing reference level : 1.5V
4. Output timing reference level :
+/-200mV (the level displacement from
stable output voltage level)
5. Output load C_L = 5pF + 1TTL Load

Timing Waveforms

Read Cycle 1 (Note 1, 3)



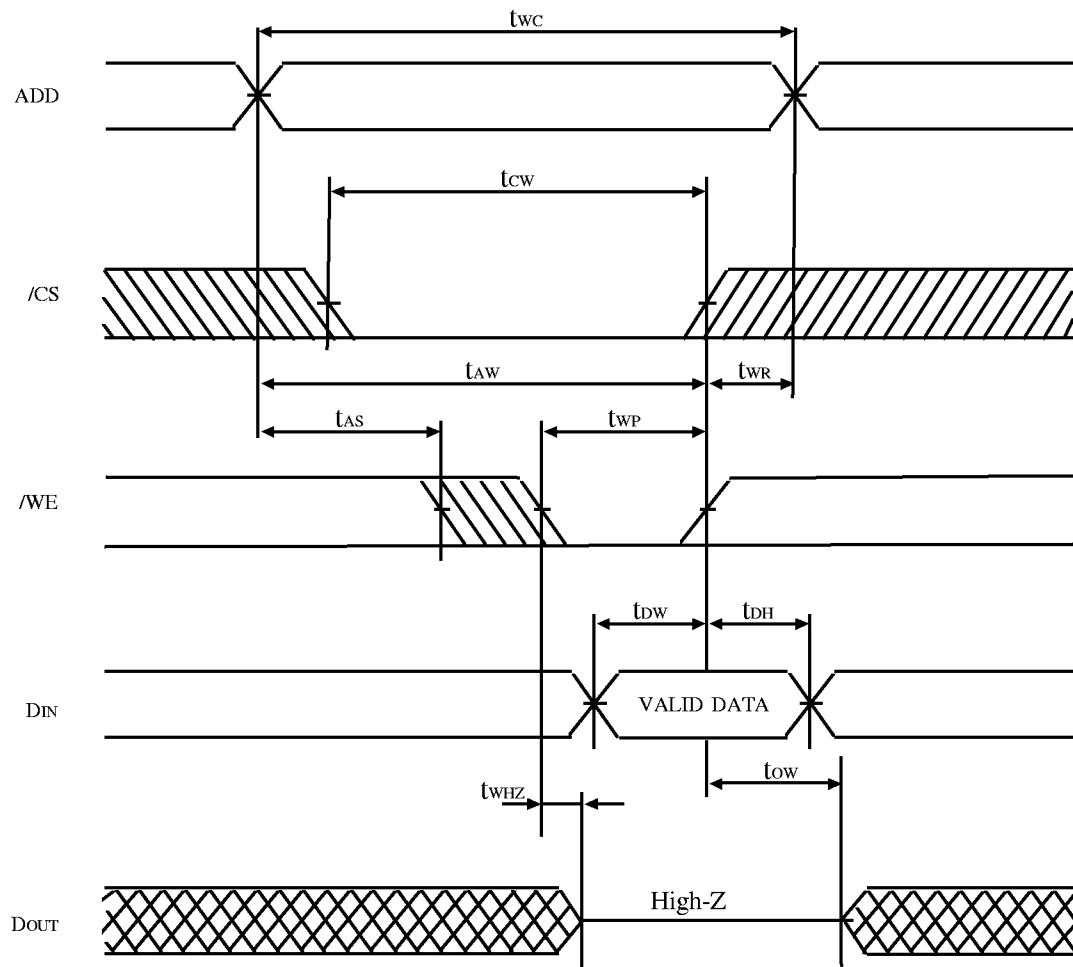
Read Cycle 2 (Note 2, 3)



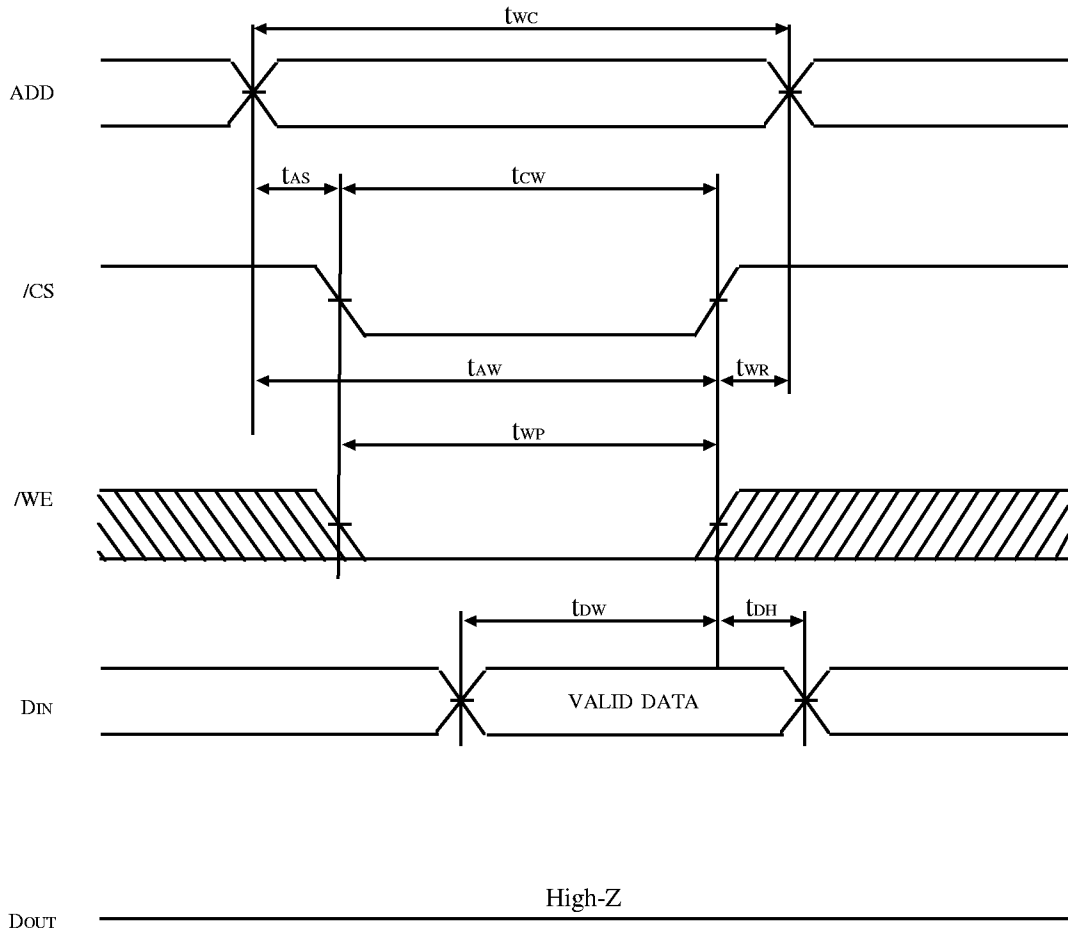
Notes:

1. Device is continuously selected. $/OE, /CS \leq V_{IL}$.
2. Address valid prior to or coincident with $/CS$ transition low.
3. $/WE$ is high for read cycle.

Write Cycle 1 (/WE Controlled) (Note 1, 2)



Write Cycle 2 (/CS Controlled) (Note 1, 2, 3)



Notes:

1. The internal write time of the memory is defined by the overlap of /CS low and /WE low. Both signals must be low to initiate a write and either signal can terminate a write by going high. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
2. Data I/O is high impedance if /OE = V_{IH} .
3. If /CS goes high simultaneously with /WE high, the output remains in a high impedance state.

Capacitance

Symbol	Parameter	Test Conditions	Min	Max	Unit
C _{IN}	Input Capacitance	T _A = 25°C, f = 1MHz V _{CC} = 5.0V	-	6	pF
C _{OUT}	Output Capacitance		-	8	pF

*Note: Tested on a sample basis

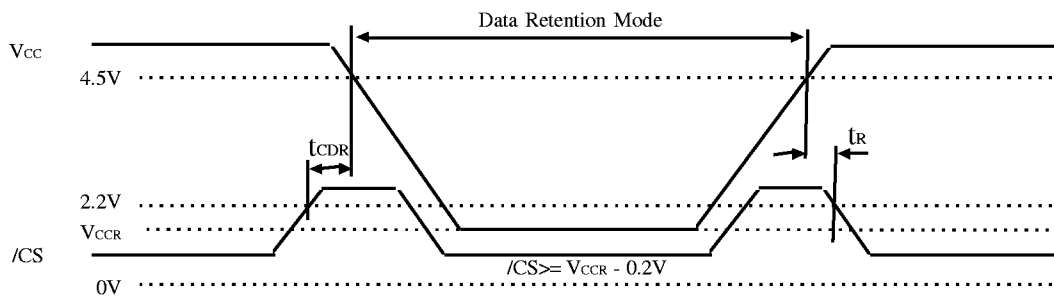
Data Retention Characteristics (T_A = 0 ~ 70°C)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V _{CCR}	Data Retention Supply Voltage	/CS>=V _{CCR} - 0.2V	2.0	-	5.5	V
I _{CCR}	Data Retention Current	V _{CC} = 3.0V /CS>=2.8V	CL	-	1 ^{*2}	uA
			CLL	-	0.5 ^{*2}	
t _{CDR}	Chip Select to Data Retention Time	Refer to the figure below	0	-	-	ns
t _R	Operation Recovery Time		t _{RC} ^{*1}	-	-	ns

Notes:

1. Read Cycle Time
2. Typ, Values are measured at 25°C

Data Retention Timing

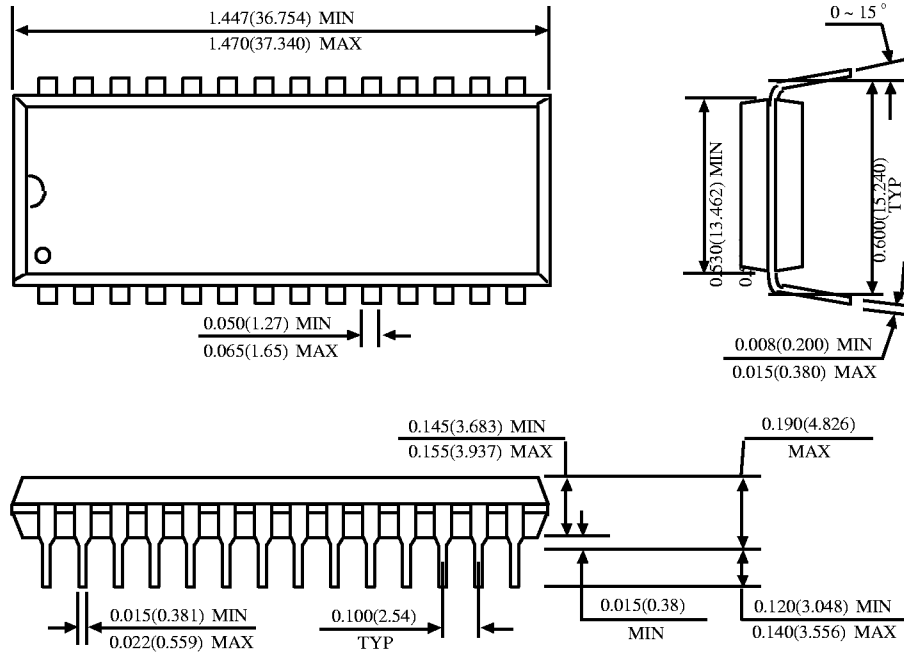


*Note: When retaining data in standby mode, supply voltage can be lowered within a certain range.
Read or write cycle cannot be performed while the supply voltage is low.

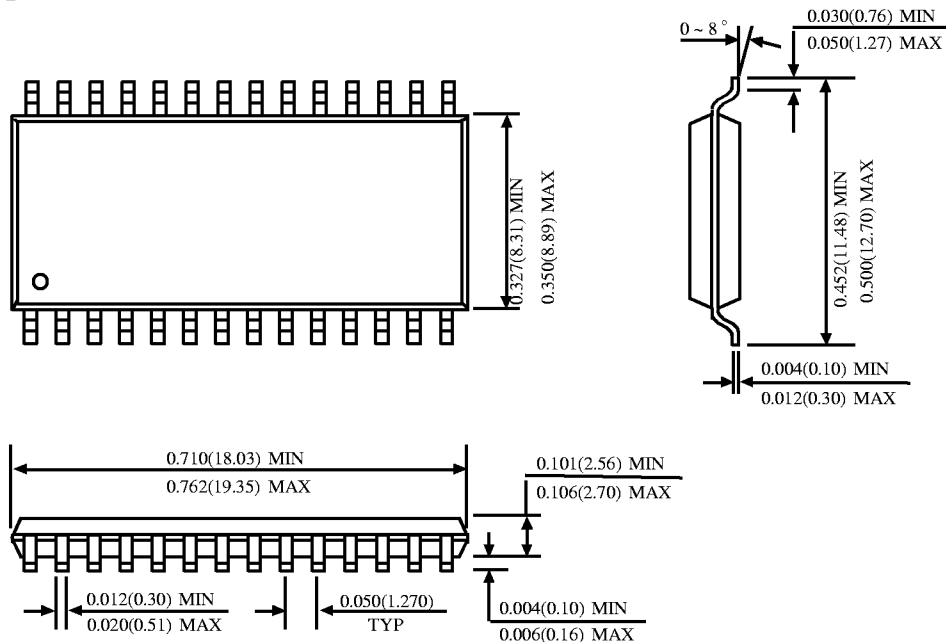
Package Dimensions

Unit: Inches (mm)

28 DIP



28 SOP



Unit: Inches (mm)

28 TSOP-I

